



2823 *EP*  
PATENT

Atty. Dkt. No. AMAT/5619/DSM/LOWK/JW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Nguyen, et al.

Serial No.: 09/912,103

Confirmation No.: 4476

Filed: July 23, 2001

For: Selective Etching of  
Organosilicate Films Over  
Silicon Oxide Stop Etch  
Layers

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§ Group Art Unit: 2823  
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Examiner: Khiem D. Nguyen

MAIL STOP AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>May 26, 2005</u> , with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
May <u>20</u> , 2005 Date	<u><i>Khiem D. Nguyen</i></u> Signature

**RESPONSE TO OFFICE ACTION DATED MARCH 31, 2005**

In response to the Office Action dated March 31, 2005, having a shortened statutory period for response set to expire on June 30, 2005, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicants believe that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5619/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper. **Remarks** begin on page 6 of this paper.